

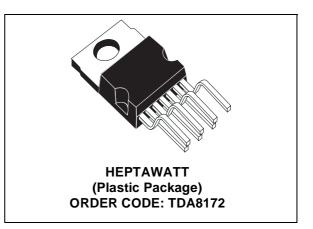
TV VERTICAL DEFLECTION OUTPUT CIRCUIT

FEATURES

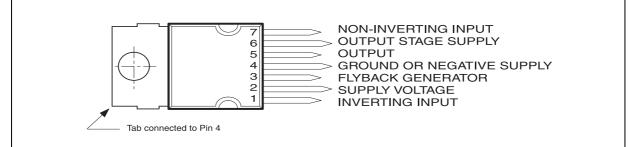
- Power Amplifier
- Flyback Generator
- Thermal Protection

DESCRIPTION

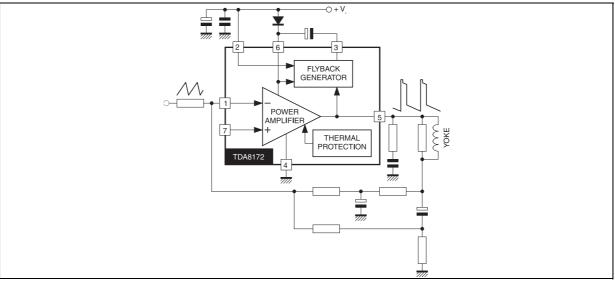
The TDA8172 is a monolithic integrated circuit in HeptawattTM package. It is a high efficiency power booster for direct driving of vertical windings of TV yokes. It is intended for use in color and black & white television as well as in monitors and displays.



PIN CONNECTION (top view)



BLOCK DIAGRAM



1 ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
VS	Supply Voltage (pin 2)	35	V	
V ₅ , V ₆	Flyback Peak Voltage	60	V	
V ₃	Voltage at Pin 3 (see Note 1)	V _S +3	V	
V ₁ , V ₇	Amplifier Input Voltage	V _S - 0.5	V	
I ₀	Output Peak Current (non repetitive, t = 2ms)	2.5	А	
I ₀	Output Peak Current at f = 50 to 200 Hz, t \leq 10µs	±5	А	
I ₀	Output Peak Current at f = 50 to 200 Hz, t > 10µs	2	Α	
l ₃	Pin 3 DC Current at $V_5 < V_2$	100	mA	
l ₃	Pin 3 Flyback Current at f = 50 to 200 Hz, $t_{fly} \le 1.5$ ms	±1.5	Α	
l ₃	Pin 3 Sink Current at f = 50 to 200 Hz, t \leq 10µs	5	Α	
P _{tot}	Total Power Dissipation at T _{case} = 90 °C	20	W	
T _{stg} , T _j	Storage and Junction Temperature	-40, +150	°C	

Note 1: This occurs during the first part of flyback pulse

2 THERMAL DATA

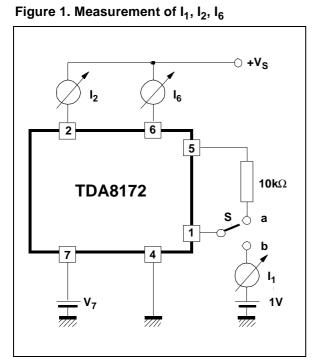
Symbol	Parameter	Value	Unit
R _{th(j-c)}	Thermal Resistance Junction-case	3	°C/W

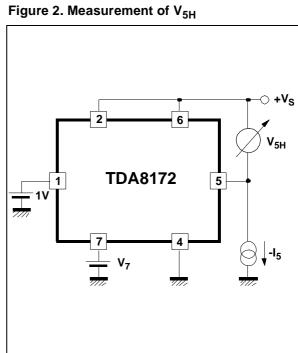
3 ELECTRICAL CHARACTERISTICS

(refer to the test circuits, V_S = 35V, T_{amb} = 25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	Fig.
l ₂	Pin 2 Quiescent Current	$I_3 = 0, I_5 = 0$		8	16	mA	1
l ₆	Pin 6 Quiescent Current	$I_3 = 0, I_5 = 0$		16	36	mA	1
l ₁	Amplifier Input Bias Current	V ₁ = 1 V, V ₇ = 2 V		- 0.1	- 1	μA	1
		V ₁ = 2 V, V ₇ = 1 V		- 0.1	- 1	μA	1
V _{3L}	Pin 3 Saturation Voltage to GND	l ₃ = 20 mA		1	1.5	V	3
V_5	Quiescent Output Voltage	$V_{S} = 35V$, $R_{a} = 39 \text{ k}\Omega$		18		V	4
V _{5L}	Output Saturation Voltage to GND	I ₅ = 1.2 A		1	1.4	V	3
		I ₅ = 0.7 A		0.7	1	V	3
V_{5H}	Output Saturation Voltage to Supply	- I ₅ = 1.2 A		1.6	2.2	V	2
		- I ₅ = 0.7 A		1.3	1.8	V	2
Тj	Junction Temperature for Thermal Shutdown			140		°C	

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S1: (a) I2 and I6 ; (b) I1

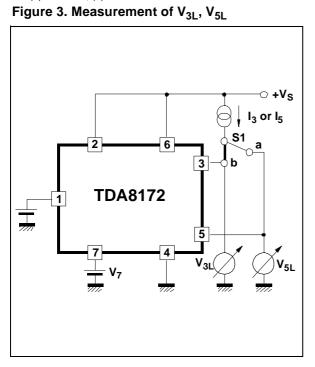
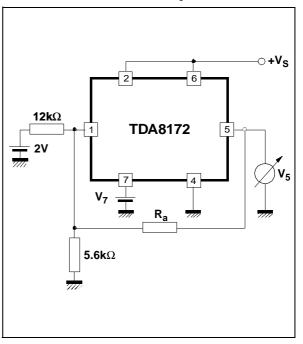


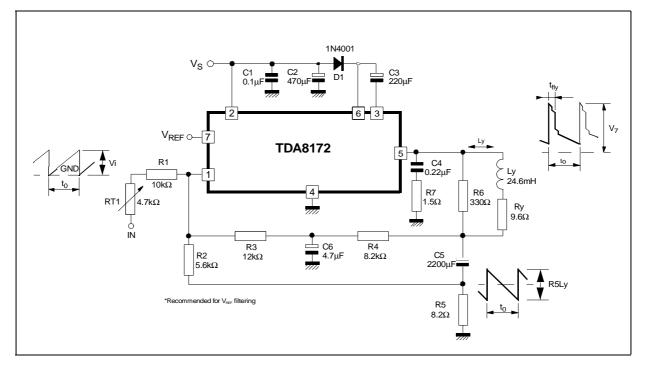
Figure 4. Measurement of V_5



S: (a) V3L ; (b) V5L



Figure 5. AC test circuit



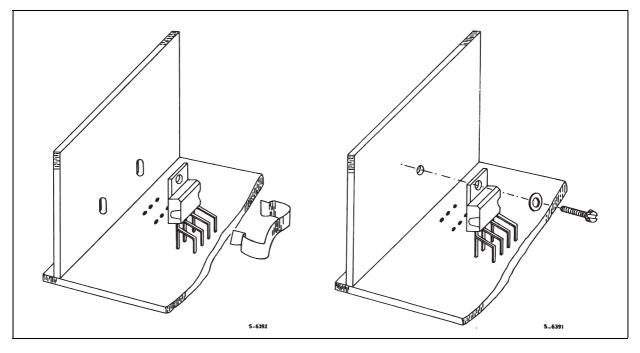
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4 MOUNTING INSTRUCTIONS

The power dissipated in the circuit is removed by adding an external heatsink. With the HEPTAWATT[™] package, the heatsink is simply attached with a screw or a compression spring (clip).

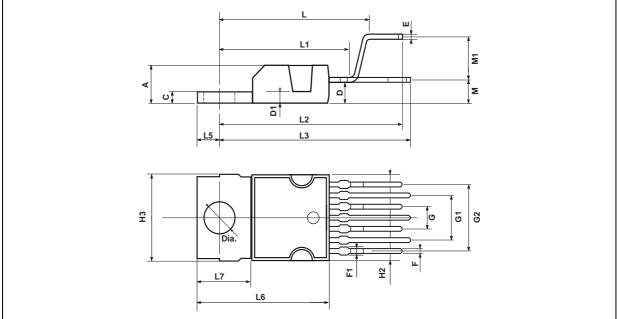
A layer of silicon grease inserted between heatsink and package optimizes thermal contact ; no electrical isolation is needed between the two surfaces since the tab is connected to Pin 4 which is ground.

Figure 6. Mounting examples



5 PACKAGE MECHANICAL DATA

9 PINS - plastic heptawatt



Dimensions		Millimeters			Inches		
Dimensions	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α			4.8			0.189	
С			1.37			0.054	
D	2.4		2.8	0.094		0.110	
D1	1.2		1.35	0.047		0.053	
E	0.35		0.55	0.014		0.022	
F	0.6		0.8	0.024		0.031	
F1			0.9			0.035	
G	2.41	2.54	2.67	0.095	0.100	0.105	
G1	4.91	5.08	5.21	0.193	0.200	0.205	
G2	7.49	7.62	7.8	0.295	0.300	0.307	
H2			10.4			0.409	
H3	10.05		10.4	0.396		0.409	
L		16.97			0.668		
L1		14.92			0.587		
L2		21.54			0.848		
L3		22.62			0.891		
L5	2.6		3	0.102		0.118	
L6	15.1		15.8	0.594		0.622	
L7	6		6.6	0.236		0.260	
М		2.8			0.110		
M1		5.08			0.200		
Dia.	3.65		3.85	0.144		0.152	

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